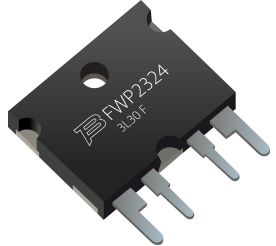


MATERIAL DECLARATION SHEET



Material Number	FWP2324 Series			
Product Line	Fixed Resistors			
Compliance Date	2025/7/22			
RoHS Compliant	No	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Plating	Tin Plating	5.28	Tin	7440-31-5	90.9	0.111	0.122
				Copper	7440-50-8	7.6	0.009	
				Silver	7440-22-4	1.5	0.002	
2	Leads	Copper	680	Copper	7440-50-8	100	15.655	15.655
3	Inside Soldering	Plating	10.56	Tin	7440-31-5	90.9	0.221	0.243
				Lead	7439-92-1	7.6	0.018	
				Silver	7440-22-4	1.5	0.004	
4	Heatsink	Anodized Aluminum	1300	Aluminum	7429-90-5	100	29.93	29.93
5	Chipbond	Filled Epoxy	100	Epoxy	25068-38-6	100	2.302	2.302
6	Substrate	Aluminum	110	Aluminum	7429-90-5	100	2.532	2.532

MATERIAL DECLARATION SHEET



7	Resistance Material	Copper alloy foil	233.8	Copper	7440-50-8	84.26	4.535	5.382
				Tin	7440-31-5	2.4	0.129	
				Manganese	7439-96-5	13.34	0.718	
8	Foildbond	Foildbond	20	Dimethylacetamide	127-19-5	100	0.46	0.46
9	Cover	Silicone Based	4	Silicon	7440-21-3	100	0.092	0.092
10	Mold	Epoxy	1880	Epoxy Black	68928-70-1	100	43.282	43.282
			Total weight	4343.64				

This Document was updated on: 2025/7/22

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Resistive material weight will be different based on the resistance value.
3. The weight of the core and coating material will differ based on the size.